



# Alan Mantooth – University of Arkansas

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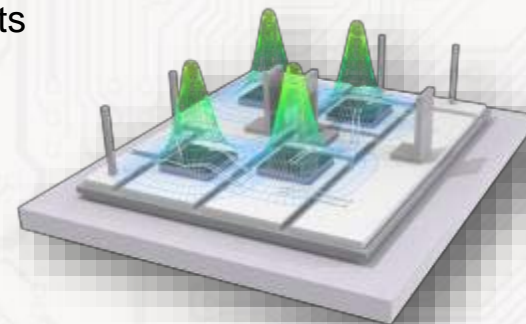
- Electronic design automation tools
- 3D Packaging
- Analog IC Design
- Semiconductor Device Modeling

<http://eleg.uark.edu/>



## PowerSynth

- Electrical and Thermal Modeling
- Fast Multi-objective Optimization of Multi-Chip Power Module Layouts
- Software Design
- Import and Export
- Physical Validation

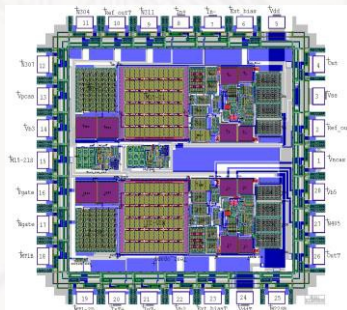


Design Automation Tools

## Analog IC Design

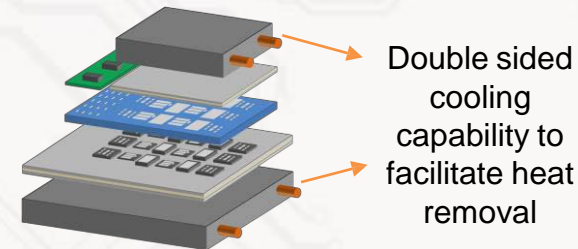
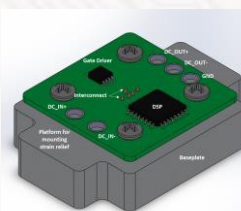
### High temperature and high efficiency integrated circuits

- Semiconductor modeling
- Model-based design approach
- Design and verification
- Physical design – layout
- Post-layout analysis
- Test over extreme temps



## 3D Packaging

### Wire bondless Integrated Power Modules



High density electronic modules, with low parasitics and ultrafast switching capability suitable for wide bandgap semiconductors